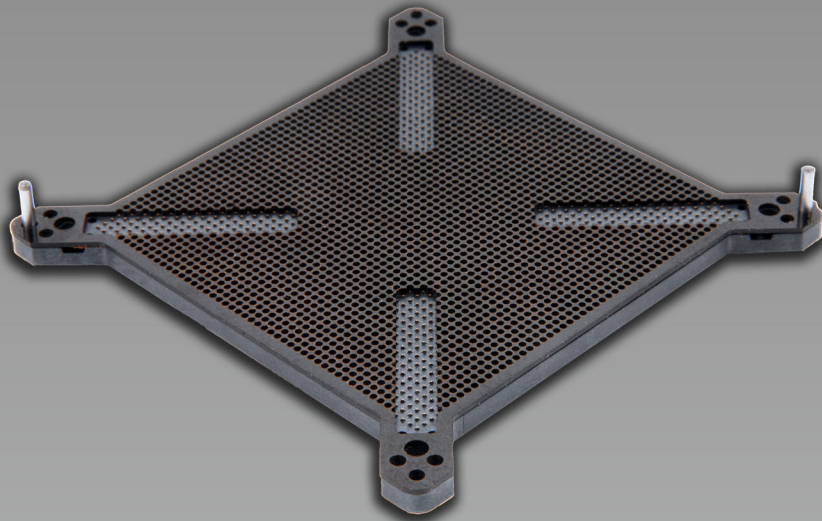
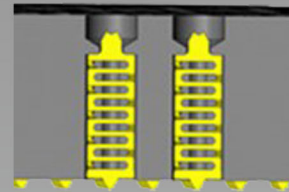


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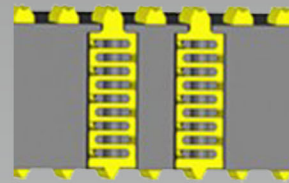
Molded GHz Sockets and Connectors for LGA, BGA, Board to Board



BGA Configuration



LGA Configuration



High Repeatability, High Durability, Low Cost

- Simple all-metal, stamped contact
- Automated manufacturing
- Standard metallurgy, materials & plating
- Long Insertion Life of 1,000+ mechanical cycles

High Density, Mounting Options

- 0.8 mm pitch in area array
- Solderless and solder-down compression mount system
- Pure vertical interface - No offset required

Bandwidth & Performance

- Twisting/ scrub action ensures good electrical contact
- Low signal loss @ 40 GHz

Ardent Concepts
www.ardentconcepts.com
info@ardentconcepts.com
603.474.1760
@ArdentConcepts

Specifications subject to change without notice



US Patent Numbers 6,787,709, 6,909,506, 7,126,062, 7,556,503, 8,926342.

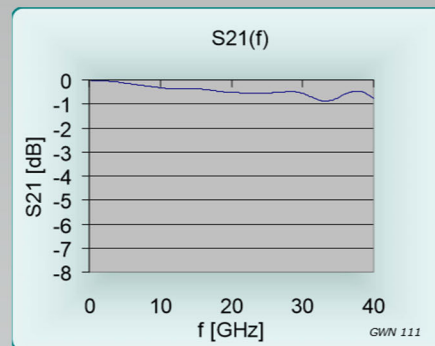
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Molded GHz Sockets and Connectors for LGA, BGA, Board to Board



	CR08-062	CR08-01
		
Contact Material	Gold Plated Beryllium Copper	Gold Plated Beryllium Copper
Mated Height	.061" (1.5 mm)	.085" (2.16 mm)
Pitch	.031" (.8 mm)	.031" (.8 mm)
Compression Force/Contact (Grams +/- 20%)	30	40
Compression Range	.010" (.25 mm)	.015" (.38 mm)
Contact Resistance	30 mΩ	50 mΩ
Inductance	.61 nH (self)	.98 nH (self)
High Freq Capacity (-1 dB point S21)	40 GHz	36 GHz
Characteristic Impedance @ Native Pitch (Ohms)	56.7 ohms	61.1 ohms
Durability	1000+ cycles	1000+ cycles
Current Carrying Capacity (single contact at 30°C)	2 A	2.63 A



Insertion Loss

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